

## REWORK METHODS FOR LEAD FREE BGA/CGA

### ABSTRACT OF THE DISCLOSURE

A method and apparatus are provided for reworking electronic component  
5 assemblies where the components are joined by solder interconnections. A cutting  
device employing a heated wire, blade or other cutting element is forced against and  
through the solder interconnections to sever the interconnections. A preferred cutting  
device employs moving the cutting element transverse to the solder interconnections to  
also provide a sawing action to the solder interconnections. Another cutting device  
10 employs a water jet to provide a high pressure stream of water that cuts and severs  
the solder interconnections.

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